

POT SERIES



SOLDERING USING SOLDER POTS

Solder is placed into the solder bath and melted. Simply dipping the required component into the melted solder in the bath provides an efficient soldering process.

Select your solder pot according to the size and purpose of component you wish to solder.

This is an introduction to the wide variety of *goot* solder pots.

goot SOLDER BATH MATERIAL

- **SUS316**

Strong against erosion among stainless steels.

- **Ceramic Coating**

Stainless Steel (SUS316) with ceramic coating. Better tolerance against erosion than regular SUS316.

- **Cast Iron**

Cost efficient and better tolerance against erosion than SUS316.

- **Ceramic**




Does not erode.







POTS ACCORDING TO USAGE

- POT-11C, 21C, 22C, 23C are used for soldering terminals and connectors, and for pre-soldering lead wires.
- POT-50C is used for soldering small PCBs, terminals and connectors, and for pre-soldering thick, heavy duty lead wires.
- POT-100C, 200C, 400C are used for solder dipping small to medium sized PCBs. The control unit for POT-400C can be separated from the bath to be incorporated into larger installations.

POT-11C / 21C / 22C / 23C : FEATURES

	goot Eutectic Solder POT Series		goot Lead-free Solder POT Series	
Model	POT-11C	POT-21C	POT-22C	POT-23C
Principal Use	Lead wire pre-soldering	Lead wire pre-soldering	Lead wire pre-soldering	Lead wire pre-soldering
RoHS Compliance	Compliant	Compliant	Compliant	Compliant
Solder Bath Shape				
Solder Bath Material	SUS316 Stainless steel		Ceramic coating	Ceramic
Selling Points	Economic. Reasonably priced		Long-life solder bath	Solder bath does not erode
Solder Melting Time (Temperature set at Max)	10 min (Settings at max.)			
Heater Type	Nichrome wire heater	Nichrome wire heater	Nichrome wire heater	Nichrome wire heater
Temperature control	Analog Open-Loop	Analog Open-Loop	Analog Open-Loop	Analog Open-Loop
Power Consumption	90W	130W	150W	130W
Solder Capacity	100g	300g	300g	300g
Bath Temperature	260-520 (approx.)	270-530 (approx.)	270-530 (approx.)	270-530 (approx.)
Internal Pot Dimensions	Φ 25x25(H)mm	Φ 36x36(H)mm	Φ 36x36(H)mm	Φ 31x39(H)mm
Life of bath (Depending on usage and environment)	3-4 months (approx.) (Using lead-free solder at 400)	3-4 months (approx.) (Using lead-free solder at 400)	1.5 years (approx.) (Using lead-free solder at 500)	No bath erosion.

POT-50 / 100 / 200 / 400C : FEATURES

	goot Eutectic solder (lead solder) bath		goot Lead-free solder bath	
Model	POT-50C	POT-400C	POT-100C/102C	POT-200C/202C
Main Use	Pre-soldering lead wires and small PCBs	Dip-soldering large PCBs	Pre-soldering lead wires and small PCBs	Pre-soldering lead wires and small PCBs
RoHS Compliance	Compliant	Compliant	Compliant	Compliant
Solder Bath Shape				
Solder Bath Material	Cast Iron	Cast Iron	SUS316 Stainless Steel (102C with ceramic coated bath suitable for lead-free solder)	SUS316 Stainless Steel (202C with ceramic coated bath suitable for lead-free solder)
Selling Points	Long-life solder bath	Long-life solder bath	Bath with ceramic coating provides longer life	Bath with ceramic coating provides longer life
	Precise temperature control	Precise temperature control	Precise temperature control	Precise temperature control
Solder Melting Time (Temperature set at Max)	50 min (Settings at max.)	60 min (Settings at 250)	40 min (Settings at 250)	40 min (Settings at 250)
Heater Type	Ceramic heater	Sheathed heater	Nichrome wire heater	Nichrome wire heater
Temperature control	PID	PID	PID	PID
Power Consumption	470-610W, 370-430W (During stable condition)	3kW	440W	720W
Solder Capacity	Approx. 850g	Approx. 50kg	Approx. 5.5kg	Approx. 9.5kg
Bath Temperature	MAX 500	MAX 350	MAX 350	MAX 400
Internal Pot Dimensions	50(W)x50(D)x50(H)mm	300(W)x400(D)x60(H)mm	91(W)x135(D)x60(H)mm	130(W)x180(D)x60(H)mm
Life of bath (Depending on usage and environment)	Still testing	Still testing	With ceramic coating approx. 2.5 years (Using lead-free solder at 350)	With ceramic coating approx. 2.5 years (Using lead-free solder at 350)

CAUTIONS WHEN USING SOLDER BATH

- Keep the solder bath temperature as low as possible. This can delay the erosion process.
- Do not scrub or hit the solder bath with sharp or hard objects that could scratch the surface. Scratches can speed up the process of erosion and cause leakage.